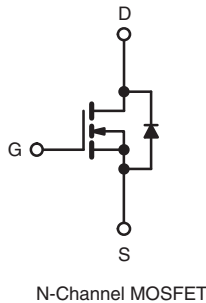
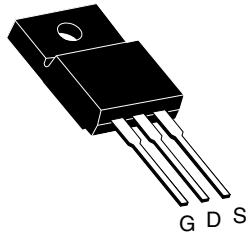


S Series Power MOSFET

| PRODUCT SUMMARY | | |
|---|-----------------|-------|
| V_{DS} at T_J max. (V) | 650 | |
| $R_{DS(on)}$ max. at 25 °C (Ω) | $V_{GS} = 10$ V | 0.190 |
| Q_g max. (nC) | 98 | |
| Q_{gs} (nC) | 17 | |
| Q_{gd} (nC) | 25 | |
| Configuration | Single | |

TO-220 FULLPAK


FEATURES

- Generation one
- High E_{AR} capability
- Lower figure-of-merit $R_{on} \times Q_g$
- 100 % avalanche tested
- Ultra low R_{on}
- dV/dt ruggedness
- Ultra low gate charge (Q_g)
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


RoHS*
Available

Note

* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non-RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details.

APPLICATIONS

- PFC power supply stages
- Hard switching topologies
- Solar inverters
- UPS
- Motor control
- Lighting
- Server telecom

| ORDERING INFORMATION | |
|----------------------|----------------|
| Package | TO-220 FULLPAK |
| Lead (Pb)-free | SiHF22N60S-E3 |


| ABSOLUTE MAXIMUM RATINGS $T_C = 25$ °C, unless otherwise noted | | | | |
|--|------------------|----------------|------|------|
| PARAMETER | SYMBOL | LIMIT | UNIT | |
| Drain-Source Voltage | V_{DS} | 600 | V | |
| Gate-Source Voltage | V_{GS} | ± 30 | | |
| Continuous Drain Current ^a | V_{GS} at 10 V | $T_C = 25$ °C | 22 | A |
| | | $T_C = 100$ °C | 13 | |
| Pulsed Drain Current ^b | I_{DM} | 65 | | |
| Linear Derating Factor | | 2 | W/°C | |
| Single Pulse Avalanche Energy ^c | E_{AS} | 690 | mJ | |
| Repetitive Avalanche Energy ^b | E_{AR} | 25 | | |
| Maximum Power Dissipation | P_D | 250 | W | |
| Drain-Source Voltage Slope | dV/dt | $T_J = 125$ °C | 37 | V/ns |
| Reverse Diode dV/dt ^e | | 5.3 | | |
| Operating Junction and Storage Temperature Range | T_J, T_{stg} | -55 to +150 | °C | |
| Soldering Recommendations (Peak Temperature) ^d | for 10 s | 300 | | |

Notes

- Limited by maximum junction temperature.
- Repetitive rating; pulse width limited by maximum junction temperature.
- $V_{DD} = 50$ V, starting $T_J = 25$ °C, $L = 28.2$ mH, $R_g = 25$ Ω , $I_{AS} = 7$ A.
- 1.6 mm from case.
- $I_{SD} \leq I_D$, $dI/dt = 100$ A/ μ s, starting $T_J = 25$ °C.



| THERMAL RESISTANCE RATINGS | | | | |
|----------------------------------|-------------------|------|------|------|
| PARAMETER | SYMBOL | TYP. | MAX. | UNIT |
| Maximum Junction-to-Ambient | R _{thJA} | - | 65 | °C/W |
| Maximum Junction-to-Case (Drain) | R _{thJC} | - | 3.4 | |

| SPECIFICATIONS T _J = 25 °C, unless otherwise noted | | | | | | | |
|---|---|---|--|------|-------|-------|------|
| PARAMETER | SYMBOL | TEST CONDITIONS | | MIN. | TYP. | MAX. | UNIT |
| Static | | | | | | | |
| Drain-Source Breakdown Voltage | V _{DS} | V _{GS} = 0 V, I _D = 1 mA | | 600 | - | - | V |
| V _{DS} Temperature Coefficient | ΔV _{DS} /T _J | Reference to 25 °C, I _D = 1 mA | | - | 0.70 | - | V/°C |
| Gate-Source Threshold Voltage (N) | V _{GS(th)} | V _{DS} = V _{GS} , I _D = 250 μA | | 2.0 | - | 4.0 | V |
| Gate-Source Leakage | I _{GSS} | V _{GS} = ± 20 V | | - | - | ± 100 | nA |
| | | V _{GS} = ± 30 V | | - | - | ± 1 | μA |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} = 600 V, V _{GS} = 0 V | | - | - | 5 | μA |
| | | V _{DS} = 600 V, V _{GS} = 0 V, T _J = 150 °C | | - | - | 100 | |
| Drain-Source On-State Resistance | R _{DS(on)} | V _{GS} = 10 V | I _D = 11 A | - | 0.160 | 0.190 | Ω |
| Forward Transconductance ^a | g _{fs} | V _{DS} = 50 V, I _D = 13 A | | - | 9.4 | - | S |
| Dynamic | | | | | | | |
| Input Capacitance | C _{iss} | V _{GS} = 0 V, V _{DS} = 25 V, f = 1.0 MHz | | - | 2810 | - | pF |
| Output Capacitance | C _{oss} | | | - | 1480 | - | |
| Reverse Transfer Capacitance | C _{rss} | | | - | 33 | - | |
| Effective Output Capacitance (Time Related) | C _{oss eff. (TR)} ^a | V _{GS} = 0 V | V _{DS} = 0 V to 480 V | - | 155 | - | |
| Total Gate Charge | Q _g | V _{GS} = 10 V | I _D = 22 A, V _{DS} = 480 V | - | 75 | 110 | nC |
| Gate-Source Charge | Q _{gs} | | | - | 17 | - | |
| Gate-Drain Charge | Q _{gd} | | | - | 25 | - | |
| Turn-On Delay Time | t _{d(on)} | V _{DD} = 380 V, I _D = 22 A, R _g = 9.1 Ω, V _{GS} = 10 V | | - | 24 | 50 | ns |
| Rise Time | t _r | | | - | 68 | 100 | |
| Turn-Off Delay Time | t _{d(off)} | | | - | 77 | 115 | |
| Fall Time | t _f | | | - | 59 | 90 | |
| Gate Input Resistance | R _g | f = 1 MHz, open drain | | - | 0.65 | - | Ω |
| Drain-Source Body Diode Characteristics | | | | | | | |
| Continuous Source-Drain Diode Current | I _S | MOSFET symbol showing the integral reverse p - n junction diode  | | - | - | 22 | A |
| Pulsed Diode Forward Current | I _{SM} | | | - | - | 88 | |
| Diode Forward Voltage | V _{SD} | T _J = 25 °C, I _S = 22 A, V _{GS} = 0 V | | - | - | 1.2 | V |
| Reverse Recovery Time | t _{rr} | T _J = 25 °C, I _F = I _S , di/dt = 100 A/μs, V _R = 25 V | | - | 462 | 690 | ns |
| Reverse Recovery Charge | Q _{rr} | | | - | 8.3 | 16 | μC |
| Reverse Recovery Current | I _{RRM} | | | - | 30 | 60 | A |

Note

a. C_{oss eff. (TR)} is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS}.

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

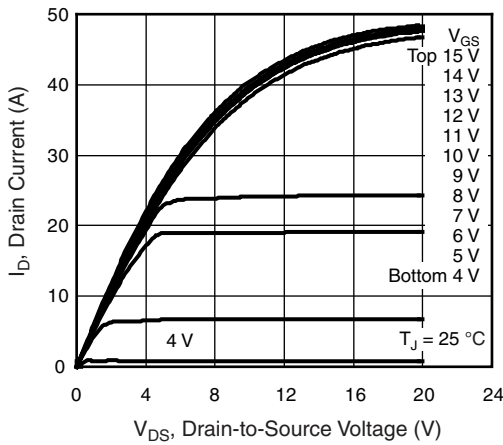


Fig. 1 - Typical Output Characteristics, $T_J = 25\text{ }^\circ\text{C}$

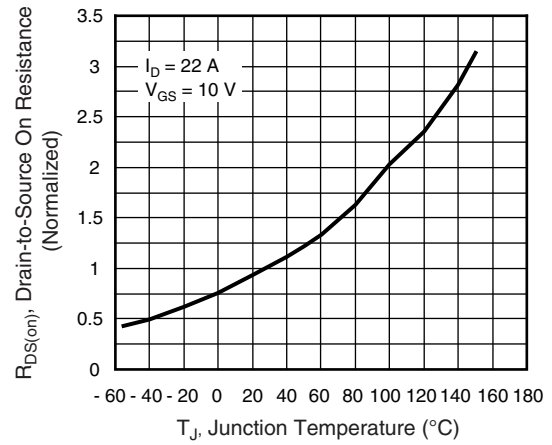


Fig. 4 - Normalized On-Resistance vs. Temperature

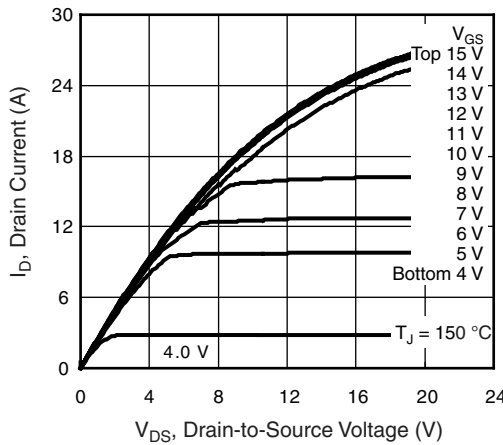


Fig. 2 - Typical Output Characteristics, $T_J = 150\text{ }^\circ\text{C}$

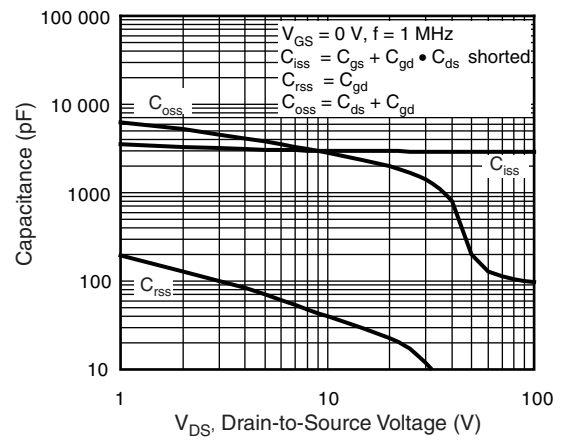


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

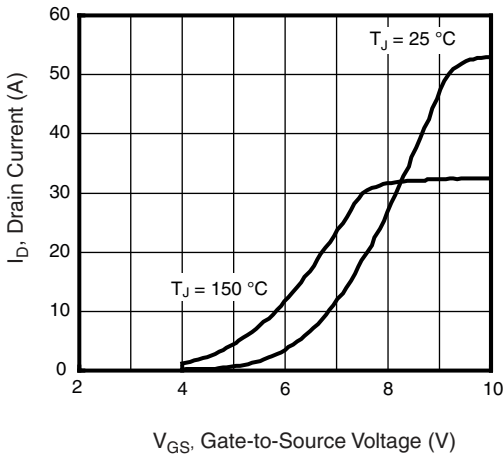


Fig. 3 - Typical Transfer Characteristics

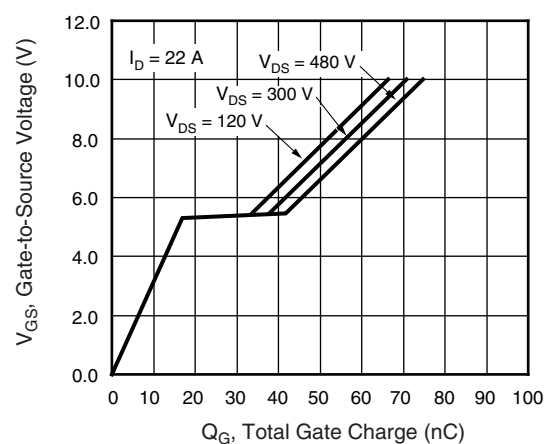


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

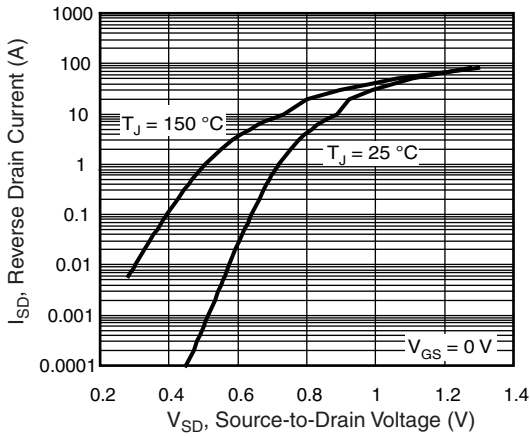


Fig. 7 - Typical Source-Drain Diode Forward Voltage

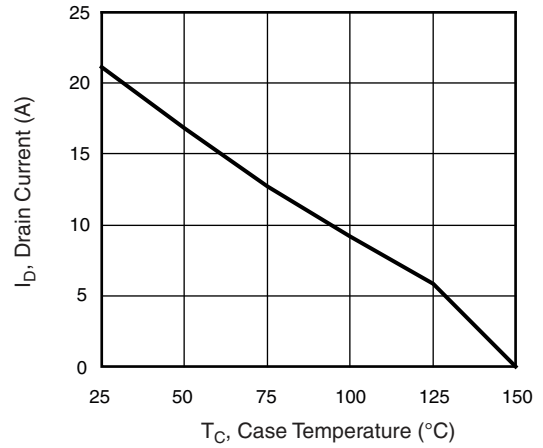


Fig. 9 - Maximum Drain Current vs. Case Temperature

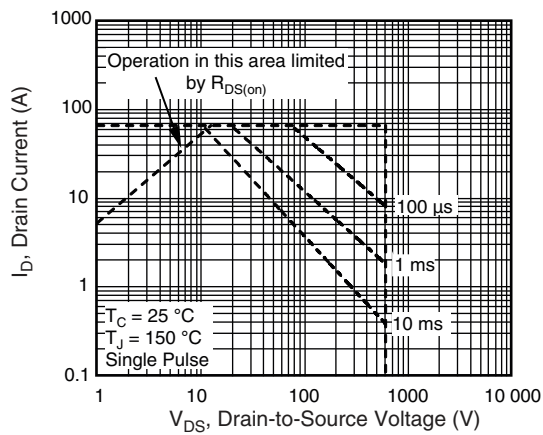


Fig. 8 - Maximum Safe Operating Area

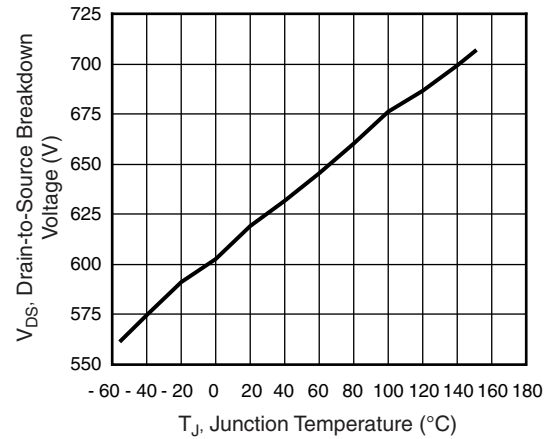


Fig. 10 - Drain-to-Source Breakdown Voltage

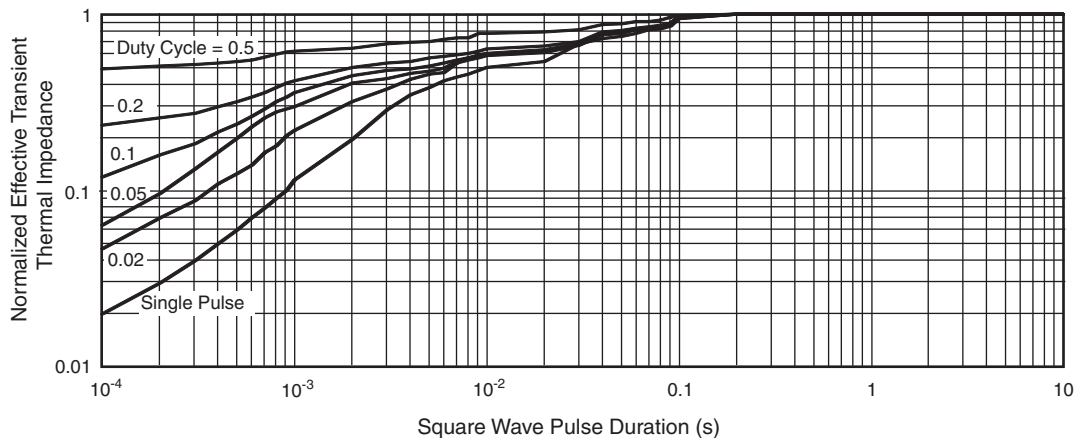


Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case

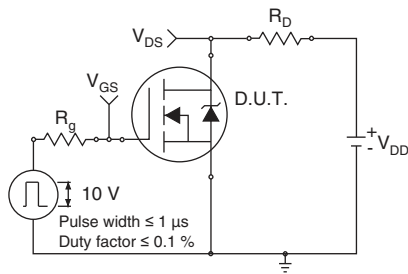


Fig. 12 - Switching Time Test Circuit

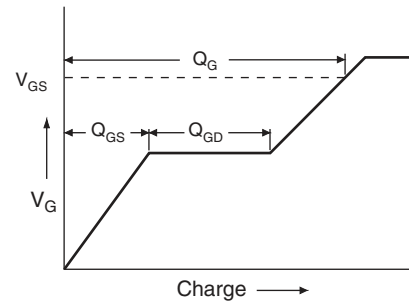


Fig. 16 - Basic Gate Charge Waveform

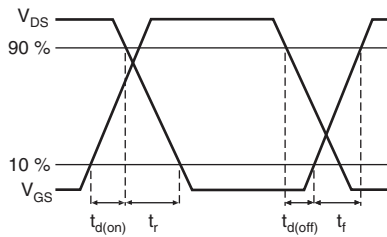


Fig. 13 - Switching Time Waveforms

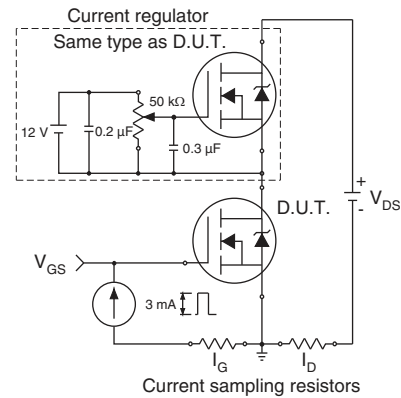


Fig. 17 - Gate Charge Test Circuit

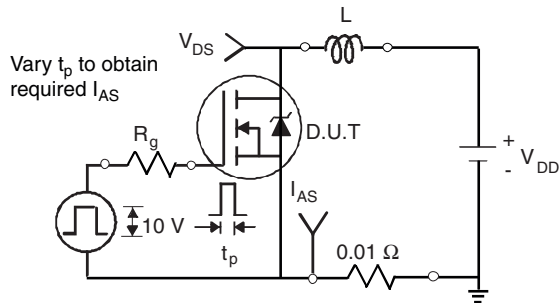


Fig. 14 - Unclamped Inductive Test Circuit

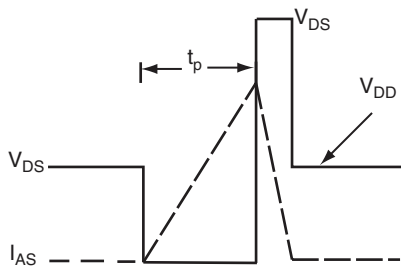
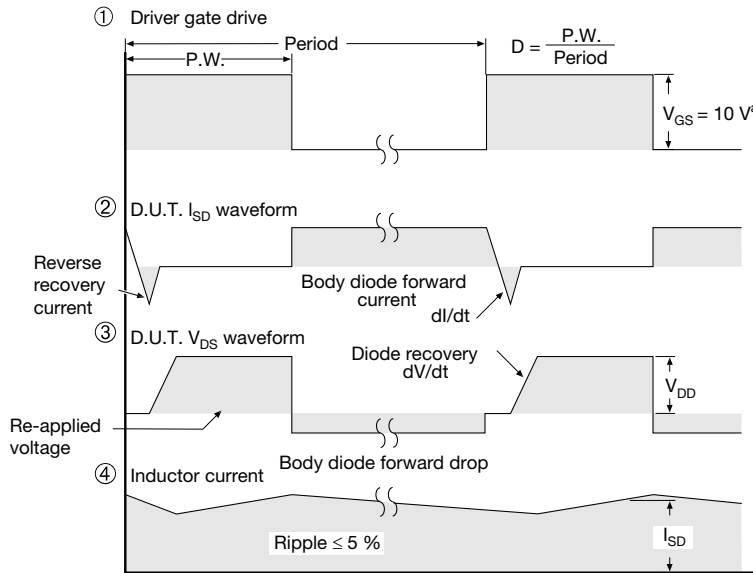
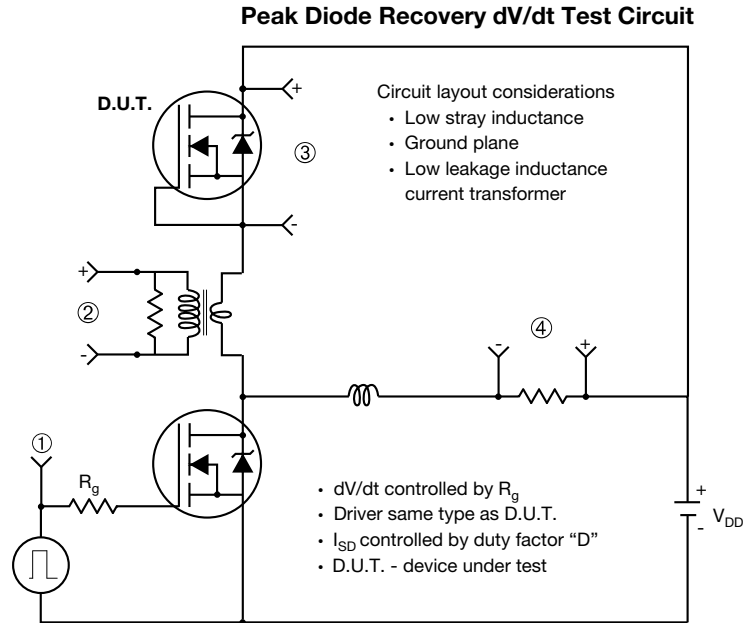


Fig. 15 - Unclamped Inductive Waveforms



Note

a. $V_{GS} = 5\text{ V}$ for logic level devices

Fig. 18 - For N-Channel

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